

REMARKS

I. Introduction

In response to the Office Action dated December 13, 2007, Applicants have amended claim 27 to more particularly point out and distinctly claim the subject matter of the invention. Care has been taken to avoid the introduction of new matter. In view of the foregoing amendments and the following remarks, Applicants respectfully submit that all pending claims are in condition for allowance.

II. Claim Rejections Under 35 U.S.C. § 112

Claims 27 – 29 and 31 stand rejected under 35 U.S.C. § 112, first paragraph, as allegedly failing to comply with the written description requirement. Moreover, claims 27 – 29 and 31 have been rejected under § 112, first paragraph, as allegedly not “reasonably” provide enablement for forming the module component. Claims 27 – 29 have further been rejected under 35 U.S.C. § 112, second paragraph, as allegedly being indefinite, and also being incomplete for omitting the allegedly necessary steps of “a primary molding-die-forming step and die-peeling, shaping step.” Applicants traverse these rejections for at least the following reasons.

First, regarding the written description requirement, the Examiner asserts that the disclosure, as originally filed, failed to provide support for “a secondary molding step of filling a second molding die ... component” and further asserts that the specification supports “filling a third molding die with resin.” Applicants respectfully submit that a “second” molding die is a molding die other than the “first” molding die. Thus, as the Examiner has correctly acknowledged that the specification supports filing a molding die other than the first molding

die, the features of claim 27 are clearly supported by the specification. Nonetheless, Applicants have amended claim 27 to recite filling the area between the first molding die and the second molding die with a first resin and filling the area between the second molding die and the third molding die with a second resin. Each of these steps is fully supported by the specification, for example, in Figure 9 and the related portions of the specification.

Regarding the lack of enablement argument, Applicants have amended claim 27, as described above, to recite a first, second, and a third molding die.

Regarding the § 112, second paragraph rejections, Applicants have amended claim 27 to more particularly point out that the first molding die is peeled from the chip component. Moreover, the phrase “and the chip component are molded with the resin” has been deleted from the claim. The Examiner also questions what “a molded element” refers to. Clearly, this refers to the chip components after molding (see, e.g., Fig. 9(g)). Finally, regarding the alleged omission of essential steps, claim 27, as amended, recites a second peeling step which removes the second and third molding dies.

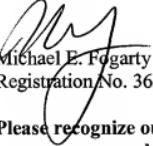
III. Conclusion

In view of the above amendments and remarks, Applicants submit that this application should be allowed and the case passed to issue. If there are any questions regarding this Amendment or the application in general, a telephone call to the undersigned would be appreciated to expedite the prosecution of the application.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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